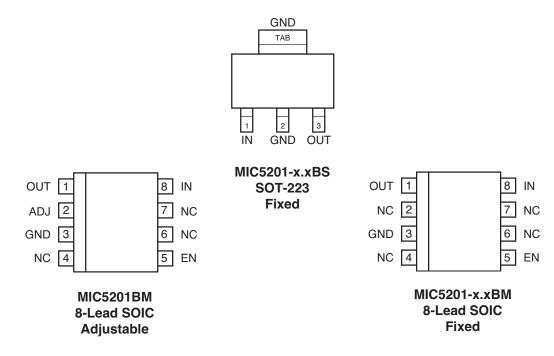
Pin Configuration



Pin Description

Pin No. SOT-223	Pin No. SO-8 Adj.	Pin No. SO-8 Fixed	Pin Name	Pin Function
3	1	1	OUT	Regulated Output
	2		ADJ	Feedback Input: (Adjustable version only)
	4, 6, 7	2, 4, 6, 7	NC	not internally connected: Connect to ground plane for lowest thermal resistance.
2	3	3	GND	Ground
	5	5	EN	Enable (Input): TTL compatible input. High = enable. Low or open = off/disable.
1	8	8	V _{IN}	Unregulated Supply Input

Absolute Maximum Ratings

Supply Input Voltage (V _{IN}) Fixed	20V to +60V
Supply Input Voltage (V _{IN}) Adjustable	–20V to +20V
Enable Input Voltage (V _{EN}) Fixed	–20V to +60V
Enable Input Voltage (V _{EN}) Adjustable	–20V to +20V
Power Dissipation (P _D)	. Internally Limited
Junction Temperature (T _J)	. –40°C to +125°C
Lead Temperature (soldering, 5 sec.)	260°C

Operating Ratings

Supply Input Voltage (V _{IN}) Fixed	2.5V to +26V
Supply Input Voltage (V _{IN}) Adjustable	2.5V to +16V
Enable Input Voltage (V _{EN})	0V to V _{IN}
Junction Temperature (T.)	-40°C to +125°C

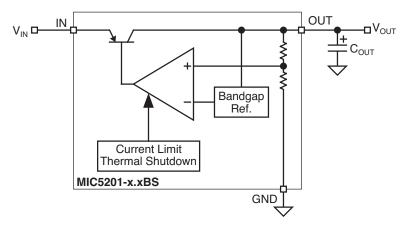
Electrical Characteristics

$ \frac{\Delta V_{O}/\Delta T}{\Delta V_{O}/V_{O}} $ $ \frac{\Delta V_{O}/V_{O}}{\Delta V_{O}/V_{O}} $ $ \frac{\Delta V_{O}/V_{O}}{V_{IN} - V_{O}} $	Output Voltage Accuracy Output Voltage Temperature Coef. Line Regulation, Fixed Line Regulation, Adjustable	Variation from specified V _{OUT} Note 2 V _{IN} = V _{OUT} + 1V to 26V	-1 -2	40	1 2	% %
$ \frac{\Delta V_{O}/V_{O}}{\Delta V_{O}/V_{O}} $ $ \frac{\Delta V_{O}/V_{O}}{V_{IN} - V_{O}} $	Line Regulation, Fixed			40	450	
$\frac{\Delta V_{O}/V_{O}}{\Delta V_{O}/V_{O}}$ $\frac{\Delta V_{O}/V_{O}}{V_{IN}-V_{O}}$		V _{IN} = V _{OUT} + 1V to 26V		1	150	ppm/°C
$\frac{\Delta V_{O}/V_{O}}{V_{IN}-V_{O}}$	Line Regulation, Adjustable	1		0.004	0.20 0.40	% %
V _{IN} – V _O		V _{IN} = V _{OUT} + 1V to 16V		0.004	0.20 0.40	% %
	Load Regulation	I _L = 0.1mA to 200mA, Note 3		0.04	0.16 0.30	% %
I	Dropout Voltage, Note 4	$\begin{split} I_L &= 100 \mu A \\ I_L &= 20 m A \\ I_L &= 50 m A \\ I_L &= 100 m A \\ I_L &= 200 m A \end{split}$		17 130 180 225 270	400	mV mV mV mV
I _{GND}	Quiescent Current	V _{ENABLE} ≤ 0.7V (shutdown)		0.01		μΑ
I _{GND}	Ground Pin Current	$I_{L} = 100 \mu A$ $I_{L} = 20 m A$ $I_{L} = 50 m A$ $I_{L} = 100 m A$ $I_{L} = 200 m A$		130 270 500 1000 3000	400 2000	μΑ μΑ μΑ μΑ μΑ
PSRR	Ripple Rejection			75		dB
I _{GNDDO}	Ground Pin Current at Dropout	$V_{IN} = 0.5V$ less than specified V_{OUT} , $I_L = 100 \mu A$, Note 5		270	330	μА
I _{LIMIT}	Current Limit	V _{OUT} = 0V		280	500	mA
$\Delta V_{O}/\Delta P_{D}$	Thermal Regulation	Note 6		0.05		%/W
e _n	Output Noise			100		μV
Enable Input						
$\overline{V_{IL}}$	Input Voltage Level	logic low (off)			0.7	V
V _{IH}	Input Voltage Level	logic high (on)	2.0			V
	Enable Input Current	V _{IL} ≤ 0.7V		0.01	1	μА
I	Enable Input Current	V _{IH} ≤ 2.0V		15	50	μΑ
	C5201 Adjustable Version Only)					
V _{REF}	Reference Voltage		1.223	1.242	1.255 1.267	V
I _{IL}			1.217	1	1.207	I *

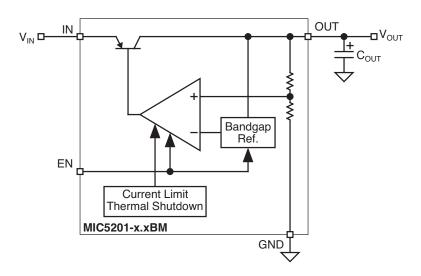
General Note: Devices are ESD sensitive. Handling precautions recommended.

- Note 1: Absolute maximum ratings indicate limits beyond which damage to the component may occur. Electrical specifications do not apply when operating the device outside of its rated operating conditions. The maximum allowable power dissipation is a function of the maximum junction temperature, $T_{J(max)}$, the junction-to-ambient thermal resistance, θ_{JA} , and the ambient temperature, T_A . The maximum allowable power dissipation at any ambient temperature is calculated using: $P_{(max)} = (\overline{J_{(max)}} \overline{A^J} \div \theta_{JA})$. Exceeding the maximum allowable power dissipation will result in excessive die temperature, and the regulator will go into thermal shutdown. The θ_{JC} of the MIC5201-x.xBS is 15°C/W and θ_{JA} for the MIC5201BM is 160°C/W mounted on a PC board (see "Thermal Considerations" section for further details).
- Note 2: Output voltage temperature coefficient is defined as the worst-case voltage change divided by the total temperature range.
- Note 3: Regulation is measured at constant junction temperature using low duty cycle pulse testing. Parts are tested for load regulation in the load range from 0.1mA to 200mA. Changes in output voltage due to heating effects are covered by the thermal regulation specification.
- Note 4: Dropout Voltage is defined as the input to output differential at which the output voltage drops 2% below its nominal value measured at 1V differential
- **Note 5:** Ground pin current is the regulator quiescent current plus pass transistor base current. The total current drawn from the supply is the sum of the load current plus the ground pin current.
- Note 6: Thermal regulation is defined as the change in output voltage at a time "t" after a change in power dissipation is applied, excluding load or line regulation effects. Specifications are for a 200mA load pulse at V_{IN} = 26V for fixed and V_{IN} = 16V for adjustable at t = 10ms.

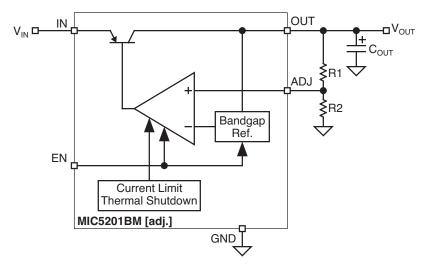
Block Diagrams



Fixed Regulator (SOT-223 version only)

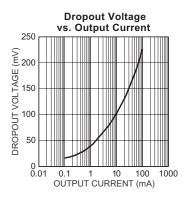


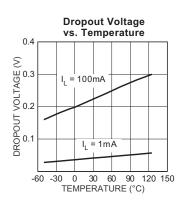
Fixed Regulator

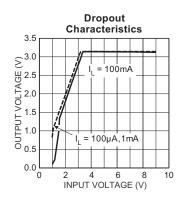


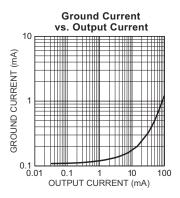
Adjustable Regulator

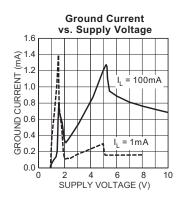
Typical Characteristics

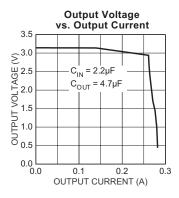


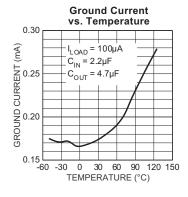


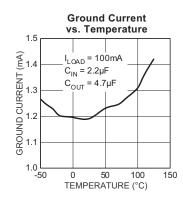


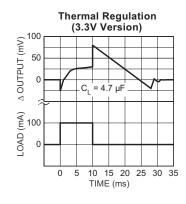


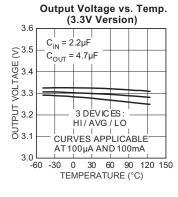


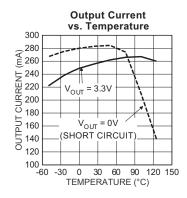


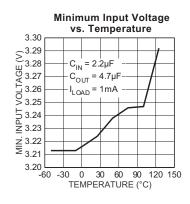


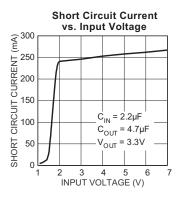


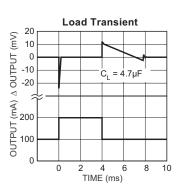


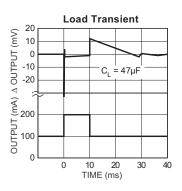


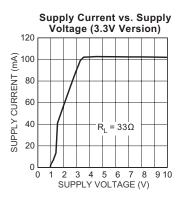


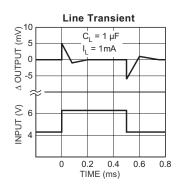


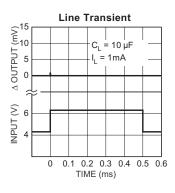


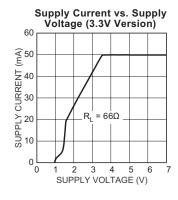


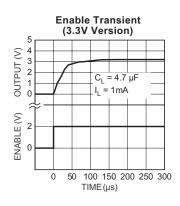


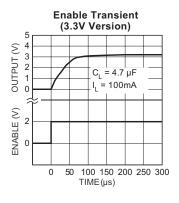


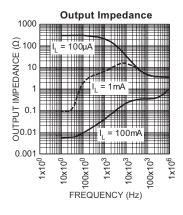


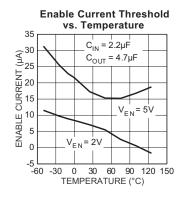


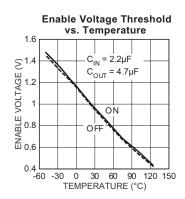


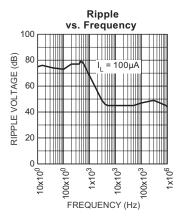


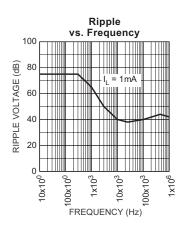


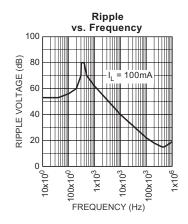












Applications Information

Figure 1 shows a basic fixed-voltage application with the unused enable input connected to V_{IN} .

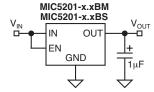


Figure 1. Fixed Application

Adjustable regulators require two resistors to set the output voltage. See Figure 2.

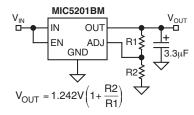


Figure 2. Adjustable Application

Resistors values are not critical because ADJ (adjust) has a high impedance, but for best results use resistors of $470k\Omega$ or less.

Output Capacitors

A 1 μF capacitor is recommended between the MIC5201 output and ground to prevent oscillations due to instability. Larger values serve to improve the regulator's transient response. Most types of tantalum or aluminum electrolytics will be adequate; film types will work, but are costly and therefore not recommended. Many aluminum electrolytics have electrolytes that freeze at about $-30^{\circ}C$, so solid tantalums are recommended for operation below $-25^{\circ}C$. The important parameters of the capacitor are an effective series resistance of about 5Ω or less and a resonant frequency above 500 kHz. The value of this capacitor may be increased without limit.

At lower values of output current, less output capacitance is required for output stability. The capacitor can be reduced to 0.47 μF for current below 10mA or 0.33 μF for currents below 1mA.

Input Capacitors

A $1\mu F$ capacitor should be placed from the MIC5201 input to ground if there is more than 10 inches of wire between the input and the ac filter capacitor or if a battery is used as the input.

Noise Reduction Capacitors

On adjustable devices, a capacitor from ADJ to GND will decrease high-frequency noise on the output. See Figure 3.

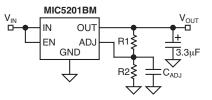


Figure 3. Decreasing Ouput Noise

Minimum Load

The MIC5201 will remain stable and in regulation with no load unlike many other voltage regulators. This is especially important in CMOS RAM keep-alive applications.

Dual-Supply Systems

When used in dual supply systems where the regulator load is returned to a negative supply, the output voltage must be diode clamped to ground.

Thermal Considerations Layout

The MIC5201-x.xBM (8-pin surface mount package) has the following thermal characteristics when mounted on a single layer copper-clad printed circuit board.

PC Board Dielectric	θ_{JA}		
FR4	160°C/W		
Ceramic	120°C/W		

Multilayer boards having a ground plane, wide traces near the pads, and large supply bus lines provide better thermal conductivity.

The "worst case" value of 160°C/W assumes no ground plane, minimum trace widths, and a FR4 material board.

Nominal Power Dissipation and Die Temperature

The MIC5201-x.xBM at a 25°C ambient temperature will operate reliably at up to 625mW power dissipation when mounted in the "worst case" manner described above. At an ambient temperature of 55°C, the device may safely dissipate 440mW. These power levels are equivalent to a die temperature of 125°C, the recommended maximum temperature for non-military grade silicon integrated circuits.

For MIC5201-x.xBS (SOT-223 package) heat sink characteristics, please refer to Micrel Application Hint 17, P.C. Board Heat Sinking.

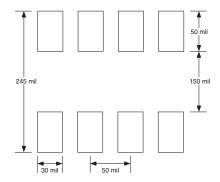
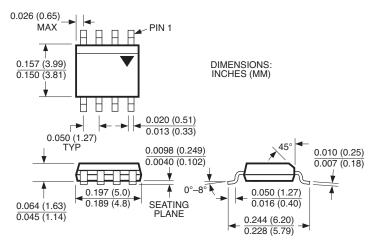
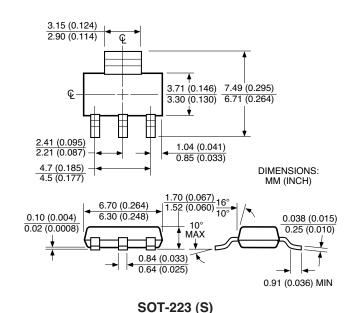


Figure 4. Min. Recommended SO-8 PCB Pads Size

Package Information



8-Pin SOP (M)



MICREL INC. 2180 FORTUNE DRIVE SAN JOSE, CA 95131 USA

TEL + 1 (408) 944-0800 FAX + 1 (408) 474-1000 WEB http://www.micrel.com

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